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onsemi - LC87F7932BUEF-2H Datasheet



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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

Details

Product Status	Active
Core Processor	-
Core Size	8-Bit
Speed	4MHz
Connectivity	SIO, UART/USART
Peripherals	LCD, POR, WDT
Number of I/O	21
Program Memory Size	32KB (32K x 8)
Program Memory Type	FLASH
EEPROM Size	
RAM Size	2K x 8
Voltage - Supply (Vcc/Vdd)	2.4V ~ 3.6V
Data Converters	A/D 7x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-BQFP
Supplier Device Package	64-QIPE (14x14)
Purchase URL	https://www.e-xfl.com/product-detail/onsemi/lc87f7932buef-2h

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Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

■Operating Temperature Range

• -40° C to $+85^{\circ}$ C

■Ports		
 Normal withsta 	nd voltage I/O ports	
Ports whose in	nput/output can be programmed in 1-bit units:	21 (P0n, P1n, P30, P70 to P73)
Multiplexed fur	nctions	
Input ports (fo	or debugger):	3 (DBGP0 (P05) to DBGP2 (P07))
LCD ports (se	gment output):	8 (P1n)
• LCD ports/gene	eral purpose I/O ports	
Segment outp	ut:	32 (S00 to S31)
Common outp	put:	4 (COM0 to COM3)
Bias power su	pply for LCD driving	5 (V1 to V3, CUP1, CUP2)
Multiplexed fur	actions	
Input/output p	oorts:	36 (LPAn, LPBn, LPCn, LPL0 to LPL3, P1n)
• Oscillator pins:		4 (CF1, CF2, XT1, XT2)
• Reset pin:		$1 (\overline{\text{RES}})$
• Power supply:		5 (V _{SS} 1, V _{SS} 2, V _{DD} 1, V _{DD} 2, V2)
■LCD Controller		
(1) Seven display	modes are available	
(2) Duty: 1/3 duty	y, 1/4 duty	
(3) Bias: 1/2 bias	, 1/3 bias	
(4) Segment/com	mon output can be switched to general purpose	I/O ports.
(5) LCD power ra	ange	-
1) 1/3 bias	V1: 1.2V to 1.8V	
	V2: 2.4V to 3.6V	
	V3: 3.6V to 5.4V	
	An LCD panel that supports the V2 ($=V_{DD}$)	\times 1.5[V] must be used when 1/3 bias is selected.
	If the supply voltage VDD is 3.0V, for example	ble, use an LCD panel that supports 4.5V.
$2 \frac{1}{2} hist$		
2) 1/2 bias	V1: 1.2V to 1.8V	
	V2: 2.4V to 3.6V	
	V3: 2.4V to 3.6V	
	(Connect V2 and V3 externally.)	

An LCD panel that supports the V2 (= V_{DD})[V] must be used when 1/2 bias is selected. If the supply voltage V_{DD} is 3.0V, for example, use an LCD panel that supports 3.0V.

■Timers

• Timer 0: 16 bit timer/counter with a capture register

Mode 0: 8-bit timer with an 8-bit programmable prescaler (with two 8-bit capture registers) \times 2 channels Mode 1: 8 bit timer with an 8-bit programmable prescaler (with an 8-bit capture register) + 8-bit counter (with an 8-bit capture register)

- Mode 2: 16 bit timer with an 8-bit programmable prescaler (with a 16-bit capture register)
- Mode 3: 16 bit counter (with a 16 bit capture register)
- Timer 1: 16 bit timer/counter that supports PWM/toggle output
 - Mode 0: 8-bit timer with an 8-bit prescaler (with toggle output) + 8-bit timer/counter (with toggle output) Mode 1: 8-bit PWM with an 8-bit prescaler × 2 channels
 - Mode 2: 16 bit timer/counter with an 8-bit prescaler (with toggle output)
 - (Toggle outputs also from the low-order 8 bits)
 - Mode 3: 16 bit timer with an 8-bit prescaler (with toggle output)
 - (The low-order 8 bits can be used as a PWM.)
- Timer 4: 8-bit timer with a 6-bit prescaler
- Timer 5: 8-bit timer with a 6-bit prescaler
- Timer 6: 8-bit timer with a 6-bit prescaler (with toggle output)
- Timer 7: 8-bit timer with a 6-bit prescaler (with toggle output)
- Base Timer
 - (1) The clock can be selected from any of the following:
 - Subclock (32.768kHz crystal oscillator/low-speed RC oscillator), system clock, and timer 0 prescaler output.
- (2) Interrupts can be generated at five specified time intervals.

■High-speed Clock Counter

- (1) Capable of counting a clock with a maximum clock rate of 8MHz (at a main clock of 4MHz).
- (2) Real-time output

■Serial Interface

- SIO0: 8-bit synchronous serial interface
 - (1) Synchronous 8-bit serial I/O (2- or 3-wire configuration, 4/3 to 512/3 tCYC transfer clock rate)
 - (2) Continuous data transfer (variable length data transfer in bit units from 1 to 256 bits, 4/3 to 512/3 tCYC transfer clock rate)
 - (3) Bi-phase modulation
 - Manchester/Bi-phase-Space data transfer
 - (4) LSB first/MSB first selectable
 - (5) SPI function: HOLD/X'tal HOLD mode release function upon receipt of a 1-byte (8-bit clock).
- SIO1: 8-bit asynchronous/synchronous serial interface
 - Mode 0: Synchronous 8-bit serial I/O (2- or 3-wire configuration, 2 to 512 tCYC transfer clock rate) Mode 1: Asynchronous serial I/O (half duplex, 8 data bits, 1 stop bit, 8 to 2048 tCYC baudrate) Mode 2: Bus mode 1 (start bit, 8 data bits, 2 to 512 tCYC transfer clock rate) Mode 3: Bus mode 2 (start detection, 8 data bits, stop detection)

■UART

- Full duplex
- Data length: 7/8/9 bits selectable
- 1 stop bit (2 bits in continuous data transmission)
- Built-in baudrate generator
- Operating mode: Programmable transfer mode, fixed-rate transfer mode
- Transfer data conversion: Normal (NRZ), Manchester encoding
- ■AD Converter: 12 bits/8 bits × 7 channels
 - 12-/8-bit AD converter resolution selectable
- Remote Control Receiver Circuit (multiplexed with the P73/INT3/T0IN pin)
 - Noise rejection function (Noise filter time constant selectable from 1/32/128 tCYC)
- ■Watchdog Timer
 - Generation of interrupt or system reset selectable
 - Two types of watchdog timer
 - (1) Watchdog timer using an external RC circuit
 - (2) Watchdog timer using the microcontroller's base timer
 - Detection intervals (1/2/4/8 seconds) can be selected for the watchdog timer that uses the base timer by configuring options.
- ■Buzzer Output
 - Generates buzzer output from P17 using the base timer.

Real Time Clock (RTC)

- (1) Uses the base timer to count the calendar years, months, days, hours, minutes, and seconds.
- (2) Calendar counts up to December 31, 2799 and calculates leap years automatically
- (3) The RTC uses the Gregorian calendar, which maintains GMT (Greenwich Mean Time).

■Internal Reset Function

- Power-on-reset (POR) function
 - (1) The POR causes a system reset only when power is turned on.

■Interrupts:

• 21 sources, 10 vectors

- (1) Provides three levels (low (L), high (H), and highest (X)) of multiplex interrupt control. Any interrupt request of the level equal to or lower than the current interrupt is not accepted.
- (2) When interrupt requests to two or more vector addresses occur at the same time, the interrupt of the highest level takes precedence over the other interrupts. For interrupts of the same level, the interrupt into the lowest vector address takes precedence.

No.	Vector Address	Level	Interrupt Source
1	00003H	X or L	INTO
2	0000BH	X or L	INT1
3	00013H	H or L	INT2/T0L
4	0001BH	H or L	INT3/base timer/RTC
5	00023H	H or L	тон
6	0002BH	H or L	T1L/T1H
7	00033H	H or L	SIO0/UART1-receive
8	0003BH	H or L	SIO1/UART-send
9	00043H	H or L	ADC/T6/T7/SPI
10	0004BH	H or L	Port 0/T4/T5

[•] Priority level: X > H > L

■Subroutine Stack Levels:

• Up to 1024 levels max. (Stack is allocated in RAM.)

■High-speed Multiplication/Division Instructions

- 16 bits \times 8 bits (5 tCYC execution time)
- 24 bits \times 16 bits (12 tCYC execution time)
- 16 bits ÷ 8 bits (8 tCYC execution time)
- 24 bits ÷ 16 bits (12 tCYC execution time)

■Oscillator Circuits

- On-chip high-speed RC oscillator: For system clock (500kHz typ)
- On-chip low-speed RC oscillator: For system clock (50kHz typ)
- CF oscillator: For system clock, Rf built in, Rd external
- Crystal oscillator: For low-speed system clock, Rf built in
- On-chip variable modulation frequency RC oscillator (VMRC): For system clock
 - (1) Adjustable in $\pm 4\%$ (typ) step from a selected center frequency
 - (2) Can measure the frequency of the source oscillator clock using an input signal from the XT1 pin as a reference.

System Clock Divider

- Low consumption current operation possible
- The minimum instruction cycle can be selected from among 750ns, 1.5µs, 3.0µs, 6.0µs, 12µs, 24µs, 48µs, 96µs, and 192µs (at a main clock rate of 4MHz).

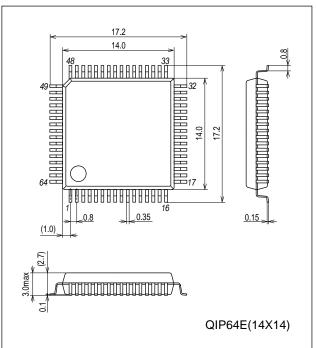
■System Clock Output

• The system clock can be output from the P04 pin.

[•] For equal priority levels, the interrupt with the lowest vector address is given priority.

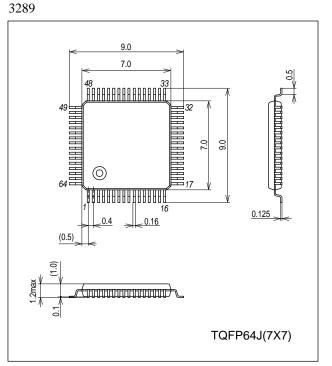
Package Dimensions

unit : mm (typ) 3159A



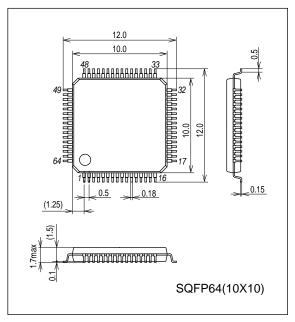
Package Dimensions

unit : mm (typ)

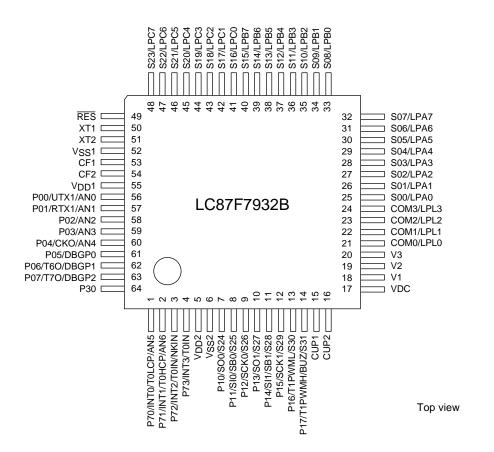


Package Dimensions

unit : mm (typ) 3190A

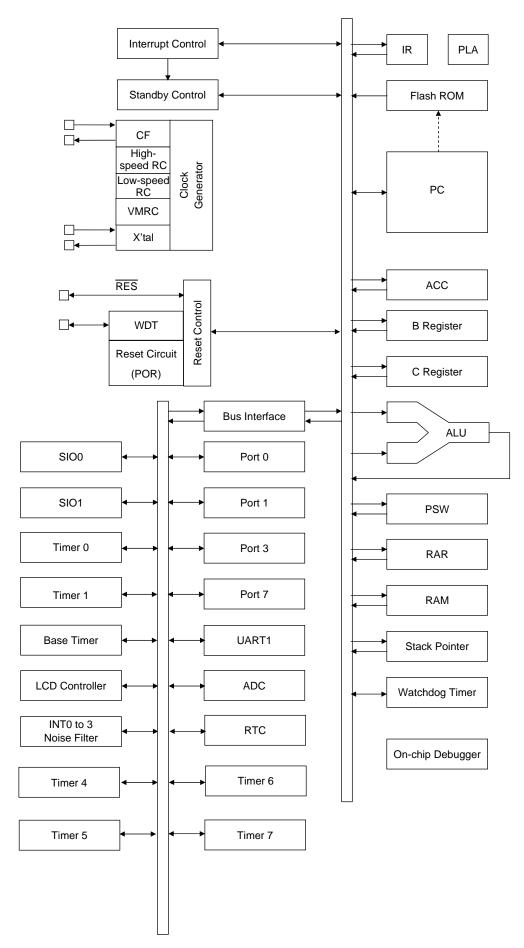


Pin Assignment



QIP64E (14×14) "Lead-and-halogen-free product" TQFP64J (7×7) "Lead-and-halogen-free product" SQFP64 (10×10) "Lead-and-halogen-free product"

System Block Diagram



User Option Table

Option Name	Option to be Applied on	Mask Version *1	Flash-ROM Version	Option Selected in Units of	Option Selection
Port output type	P00 to P07		0		CMOS
			0	1 bit	N-channel open drain
	P10 to P17		0		CMOS
			0	1 bit	N-channel open drain
	P30		0		CMOS
			0	1 bit	N-channel open drain
Base timer	Watchdog timer				1 second
watchdog timer	detection period				2 seconds
			0	-	4 seconds
			8 seconds		
Program start		*2	0		00000h
address	-	*2	0	-	07E00h

*1: Mask option selection. No change possible after mask is completed.

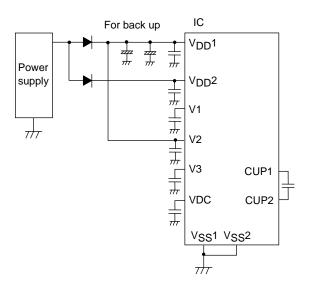
*2: Program start address of the mask version is 00000h.

*Note 1: Connect the IC as shown below to minimize noise on the $V_{DD}1$.

Be sure to electrically short the V_{SS1} and V_{SS2} .

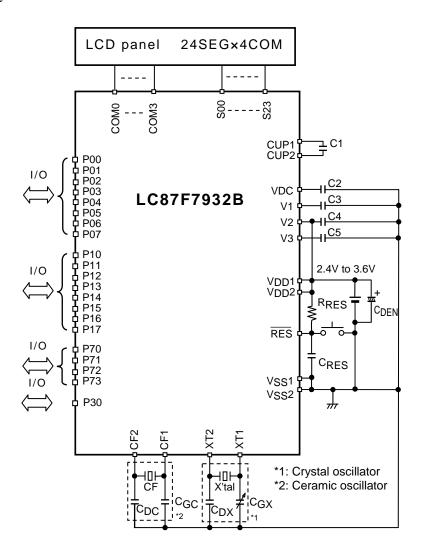
*Note 2: The power to retain the internal memory is supplied via the V2 pin. VDD1, VDD2 and V2 are used as power supply for ports. If VDD1 and VDD2 are not backed up, the output does not go high even if a high level is applied to the port latch. Therefore, if VDD1 and VDD2 are not backed up, the high level output becomes unstable in HOLD mode, and the backup time becomes shorter because a through-current flows from VDD to GND in the input buffer.

If V_{DD1} and V_{DD2} are not backed up, configure the program or set up the external circuit so that the output is held at a low level in HOLD mode to prevent an unnecessary through-current from flowing.



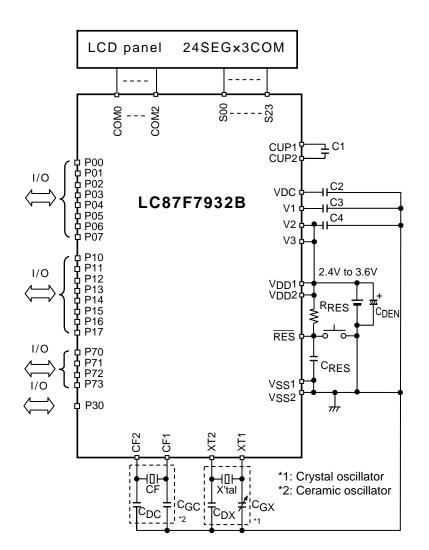
Circuit Example

(1)1/3 bias, 1/4 duty



X'tal	Crystal resonator	Refer to Page 26
C _{GX}	Trimmer capacitor	(Characteristics of a sample clock oscillator
C _{DX}	Capacitor for crystal oscillator	circuit)
CF	Ceramic resonator	Refer to Page 26
C _{GC}	Capacitor for ceramic oscillator	(Characteristics of a sample clock oscillator
C _{DC}	Capacitor for ceramic oscillator	circuit)
C1 to C5	Capacitors	0.1µF (recommended)
C _{DEN}	Electrolytic capacitor	For back up
C _{RES}	Capacitor for RES	Refer to User's manual "Reset Function"
R _{RES}	Resistor for RES	

(2)1/2 bias, 1/3 duty



X'tal	Crystal resonator	Refer to Page 26
C _{GX}	Trimmer capacitor	(Characteristics of a sample clock oscillator
C _{DX}	Capacitor for crystal oscillator	circuit)
CF	Ceramic resonator	Refer to Page 26
C _{GC}	Capacitor for ceramic oscillator	(Characteristics of a sample clock oscillator
C _{DC}	Capacitor for ceramic oscillator	circuit)
C1 to C4	Capacitors	0.1µF (recommended)
C _{DEN}	Electrolytic capacitor	For back up
C _{RES}	Capacitor for RES	Refer to User's manual "Reset Function"
R _{RES}	Resistor for RES	

	0					Specific	cation	
Parameter	Symbol	Pin/Remarks	Conditions	V _{DD} [V]	min	typ	max	unit
Operating supply voltage (Note 2-1)	V _{DD} (1)	V _{DD} 1=V _{DD} 2=V2	0.75μs≤tCYC≤200μs Normal mode		2.4		3.6	
Memory sustaining supply voltage	VHD	V _{DD} 1=V _{DD} 2=V2	RAM and register contents sustained in HOLD mode.		2.2		3.6	
High level input voltage	V _{IH} (1)	Ports 0, 3 LPA, LPB, LPC, LPL	Output disabled	2.4 to 3.6	0.3V _{DD} +0.7		V _{DD}	
Ū	V _{IH} (2)	Port 1 P71 to 73 P70 port input / interrupt side	Output disabled When INT1VTSL=0 (P71 only)	2.4 to 3.6	0.3V _{DD} +0.7		V _{DD}	
	V _{IH} (3)	P71 interrupt side	Output disabled When INT1VTSL=1	2.4 to 3.6	0.85V _{DD}		V _{DD}	
	V _{IH} (4)	P70 watchdog timer side	Output disabled	2.4 to 3.6	0.9V _{DD}		V _{DD}	V
	V _{IH} (5)	XT1, XT2, CF1, RES		2.4 to 3.6	0.75V _{DD}		V _{DD}	
Low level input voltage	V _{IL} (1)	Ports 0, 3 LPA, LPB, LPC, LPL	Output disabled	2.4 to 3.6	V _{SS}		0.2V _{DD}	
	V _{IL} (2)	Port 1 P71 to 73 P70 port input / interrupt side	Output disabled When INT1VTSL=0 (P71 only)	2.4 to 3.6	V _{SS}		0.2V _{DD}	
	V _{IL} (3)	P71 interrupt side	Output disabled When INT1VTSL=1	2.4 to 3.6	VSS		0.45V _{DD}	
	V _{IL} (4)	P70 watchdog timer side	Output disabled	2.4 to 3.6	V _{SS}		0.8V _{DD} -1.0	
	V _{IL} (5)	XT1, XT2, CF1, RES		2.4 to 3.6	V _{SS}		0.25V _{DD}	
Instruction cycle time (Note 2-2)	tCYC			2.4 to 3.6			200	μs
External system clock frequency	FEXCF(1)	CF1	 CF2 pin open System clock frequency division ratio = 1/1 External system clock duty = 50±5% 	2.4 to 3.6	0.1		4	MHz
			 CF2 pin open System clock frequency division ratio = 1/2 	2.4 to 3.6	0.2		8	
Oscillation frequency range	FmCF(1)	CF1, CF2	4MHz ceramic oscillation See Fig. 1.	2.4 to 3.6		4		MHz
(Note 2-3)	FmRC(1)		Internal high-speed RC oscillation	2.4 to 3.6	250	500	750	
	FsRC(1)		Internal low-speed RC oscillation	2.4 to 3.6	25	50	75	kHz
	FsX'tal	XT1, XT2	 32.768kHz crystal oscillation See Fig. 2. 	2.4 to 3.6		32.768		
VMRC oscillation	OpVMRC(1)		When VMSL4M=0	3.0 to 3.6	8	10	12	
usable range	OpVMRC(2)		When VMSL4M=1	2.4 to 3.6	3.5	4	4.5	MHz
VMRC oscillation adjustment range	VmADJ(1)		Each step of VMRAJn (Wide range)	2.4 to 3.6	8	24	64	%
Tango	VmADJ(2)		Each step of VMFAJn (Small range)	2.4 to 3.6	1	4	8	

Allowable Operating Conditions at Ta=-40°C to +85°C, V_{SS}1=V_{SS}2=0V

Note 2-1: V_{DD} must be held greater than or equal to 3.0V in the flash ROM onboard programming mode.

Note 2-2: Relationship between tCYC and oscillation frequency is 3/FmCF at a division ratio of 1/1 and 6/FmCF at a division ratio of 1/2.

Note 2-3: See Tables 1 and 2 for the oscillation constants.

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Parameter	Symbol	Pin/Remarks	Conditions		Specification				
	Cynibol		Conditions	V _{DD} [V]	min	typ	max	unit	
High level input current	I _{IH} (1)	Ports 0, 1, 3, 7 LPA, LPB, LPC LPL	Output disabled Pull-up resistor off VIN=VDD (Including output Tr's off leakage current)	2.4 to 3.6			1		
	I _{IH} (2)	RES	V _{IN} =V _{DD}	2.4 to 3.6			1		
	I _{IH} (3)	XT1, XT2	 Input port specification VIN=VDD 	2.4 to 3.6			1		
	I _{IH} (4)	CF1	V _{IN} =V _{DD}	2.4 to 3.6			15		
Low level input current	I _{IL} (1)	Ports 0, 1, 3, 7 LPA, LPB, LPC LPL	Output disabled Pull-up resistor off VIN=VSS (Including output Tr's off leakage current)	2.4 to 3.6	-1			μΑ	
	I _{IL} (2)	RES	V _{IN} =V _{SS}	2.4 to 3.6	-1				
	I _{IL} (3)	XT1, XT2	 Input port specification V_{IN}=V_{SS} 	2.4 to 3.6	-1				
	I _{IL} (4)	CF1	V _{IN} =V _{SS}	2.4 to 3.6	-15				
High level output	V _{OH} (1)	CMOS output ports	I _{OH} =-0.4mA	3.0 to 3.6	V _{DD} -0.4				
voltage	V _{OH} (2)	0, 1	I _{OH} =-0.2mA	2.4 to 3.6	V _{DD} -0.4				
	V _{OH} (3)	CMOS output port 3	I _{OH} =-1.6mA	3.0 to 3.6	V _{DD} -0.4				
	V _{OH} (4)		I _{OH} =-1mA	2.4 to 3.6	V _{DD} -0.4				
	V _{OH} (5)	P71 to 73	I _{OH} =-0.4mA	3.0 to 3.6	V _{DD} -0.4				
	V _{OH} (6)		I _{OH} =-0.2mA	2.4 to 3.6	V _{DD} -0.4				
	V _{OH} (7)	LPA, LPB, LPC LPL	I _{OH} =-0.1mA	2.4 to 3.6	V _{DD} -0.4				
Low level output	V _{OL} (1)	Ports 0, 1	I _{OL} =1.6mA	3.0 to 3.6			0.4		
voltage	V _{OL} (2)]	I _{OL} =1mA	2.4 to 3.6			0.4		
	V _{OL} (3)	Port 3	I _{OL} =5mA	3.0 to 3.6			0.4		
	V _{OL} (4)		I _{OL} =2.5mA	2.4 to 3.6			0.4	V	
	V _{OL} (5)	Port 7	I _{OL} =1.6mA	3.0 to 3.6			0.4		
	V _{OL} (6)	XT2	I _{OL} =1mA	2.4 to 3.6			0.4		
	V _{OL} (7)	LPA, LPB, LPC LPL	I _{OL} =0.1mA	2.4 to 3.6			0.4		
LCD output voltage deviation	VODLS	S00 to S31	 I_O=0mA V1, V2, V3 LCD level output See Fig. 8. 	2.4 to 3.6	0		±0.2		
	VODLC	COM0 to COM3	• I _O =0mA • V1, V2, V3 LCD level output • See Fig. 8.	2.4 to 3.6	0		±0.2		
Pull-up resistance	Rpu(1)	Ports 0, 1, 3, 7	V _{OH} =0.9V _{DD}	2.4 to 3.6	18	50	150	kΩ	
Hysterisis voltage	VHYS(1)	Ports 1, 7 RES		2.4 to 3.6		0.1V _{DD}		V	
Pin capacitance	СР	All pins	 For pins other than that under test: V_{IN}=V_{SS} f=1MHz Ta=25°C 	2.4 to 3.6		10		pF	

Electrical Characteristics at Ta=-40°C to +85°C, $V_{SS}1=V_{SS}2=0V$

2. SIO1 Serial I/O Characteristics (Note 4-2-1)

		D	Oursels al	Dia (Dana adua	Oracittiana			Spec	ification	
	ŀ	Parameter	Symbol	Pin/Remarks	Conditions	V _{DD} [V]	min	typ	max	unit
		Frequency	tSCK(3)	SCK1(P15)	See Fig. 6.		2			
	Input clock	Low level pulse width	tSCKL(3)			2.4 to 3.6	1			tCYC
Serial clock	lnp	High level pulse width	tSCKH(3)				1			
erial	×	Frequency	tSCK(4)	SCK1(P15)	CMOS output selected		2			
Ś	응	Low level pulse width	tSCKL(4)		• See Fig. 6.	2.4 to 3.6		1/2		tSCK
	Output	High level pulse width	tSCKH(4)				1/2			ISCK
Serial input	Da	ata setup time	tsDI(2)	SB1(P14), SI1(P14)	Must be specified with respect to the rising edge of SIOCLK.		0.03			
Serial	Da	ata hold time	thDI(2)		• See Fig. 6.	2.4 to 3.6	0.03			
Serial output	Οι	utput delay time	tdDO(4)	SO1(P13), SB1(P14)	 Must be specified with respect to the falling edge of SIOCLK. Must be specified as the time up to the beginning of output state change in open drain output mode. See Fig. 6. 	2.4 to 3.6			(1/3)tCYC +0.05	μs

Note 4-2-1: These	specifications a	re theoretical val	ues. Be sure to a	dd margin d	epending on its use.
	specifications a	ie meorement va		aa margin a	epending on no abe.

Pulse Input Conditions at $Ta = -40^{\circ}C$ to $+85^{\circ}C$, $V_{SS}1 = V_{SS}2 = 0V$

Parameter	Currents al	Pin/Remarks	Conditions			Spec	cification	
Parameter	Symbol	PIN/Remarks	Conditions	V _{DD} [V]	min	typ	max	unit
High/low level	tPIH(1)	INT0(P70),	• Interrupt source flag can be set.					
pulse width	tPIL(1)	INT1(P71),	Event inputs for timer 0	2.4 to 3.6	1			
		INT2(P72)	are enabled.					
	tPIH(2)	INT3(P73) when	• Interrupt source flag can be set.					
	tPIL(2)	noise filter time	Event inputs for timer 0 are	2.4 to 3.6	2			
		constant is 1/1	enabled.					tCYC
	tPIH(3)	INT3(P73) when	• Interrupt source flag can be set.					
	tPIL(3)	noise filter time	Event inputs for timer 0 are	2.4 to 3.6	64			
		constant is 1/32	enabled.					
	tPIH(4)	INT3(P73) when	• Interrupt source flag can be set.					
	tPIL(4)	noise filter time	Event inputs for timer 0 are	2.4 to 3.6	256			
		constant is 1/128	enabled.					
	tPIL(5)	RES	Resetting is enabled.	2.4 to 3.6	200			μs

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Consumption Current Characteristics at Ta = -40°C to +85°C, $V_{SS}1 = V_{SS}2 = 0V$

Parameter Symbol		ymbol Pin/Remarks	Conditions		Specification				
Parameter	Symbol	Pin/Remarks	Conditions	V _{DD} [V]	min	typ	max	unit	
Current consumption in normal operating mode (Note 7-1)	IDDOP(1)	V _{DD} 1=V _{DD} 2 =V2	FmCF=4MHz ceramic oscillation FsX'tal=32.768kHz crystal oscillation System clock set to 4MHz side Internal RC oscillation stopped VMRC oscillation stopped 1/1 frequency division ratio	2.4 to 3.6		2.0	4.2	mA	
	IDDOP(2)		FmCF=0Hz (Oscillation stopped) FsX'tal=32.768kHz crystal oscillation System clock set to high-speed internal RC oscillation VMRC oscillation stopped 1/1 frequency division ratio	2.4 to 3.6		250	900		
	IDDOP(3)		FmCF=0Hz (Oscillation stopped) FsX'tal=32.768kHz crystal oscillation System clock set to low-speed internal RC oscillation VMRC oscillation stopped 1/1 frequency division ratio	2.4 to 3.6		30	120	μΑ	
	IDDOP(4)		FmCF=0Hz (Oscillation stopped) FsX'tal=32.768kHz crystal oscillation Internal RC oscillation stopped System clock set to 4MHz VMRC oscillation 1/1 frequency division ratio	2.4 to 3.6		2.0	5.4	mA	
	IDDOP(5)		FmCF=0Hz (Oscillation stopped) FsX'tal=32.768kHz crystal oscillation Internal RC oscillation stopped System clock set to 500kHz VMRC oscillation 1/1 frequency division ratio	2.4 to 3.6		250	900		
IDDOP(6) IDDOP(7)		FmCF=0Hz (Oscillation stopped) FsX'tal=32.768kHz crystal oscillation System clock set to 32.768kHz side Internal RC oscillation stopped VMRC oscillation stopped 1/1 frequency division ratio Normal XT amp mode	2.4 to 3.6		20	86	μΑ		
	IDDOP(7)		FmCF=0Hz (Oscillation stopped) FsX'tal=32.768kHz crystal oscillation System clock set to 32.768kHz side Internal RC oscillation stopped VMRC oscillation stopped 1/1 frequency division ratio Low consumption XT amp mode	2.4 to 3.6		15	72		

Note 7-1: The consumption current value does not include current that flows into the output transistors and internal pull-up resistors.

Continued on next page.

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Parameter	Symbol	Pin/Remarks	Conditions		Specification				
Falametei	Symbol	Pin/Remarks	Conditions	V _{DD} [V]	min	typ	max	unit	
Current consumption in HALT mode (Note 7-1)	IDDHALT(1)	V _{DD} 1=V _{DD} 2 =V2	HALT mode • FmCF=4MHz ceramic oscillation • FsX'tal=32.768kHz crystal oscillation • System clock set to 4MHz side • Internal RC oscillation stopped • VMRC oscillation stopped • 1/1 frequency division ratio	2.4 to 3.6		0.55	1.55	mA	
	IDDHALT(2)		HALT mode • FmCF=0Hz (Oscillation stopped) • FsX'tal=32.768kHz crystal oscillation • System clock set to high-speed internal RC oscillation • VMRC oscillation stopped • 1/1 frequency division ratio	2.4 to 3.6		68	280		
	IDDHALT(3)		HALT mode • FmCF=0Hz (Oscillation stopped) • FsX'tal=32.768kHz crystal oscillation • System clock set to low-speed internal RC oscillation • VMRC oscillation stopped • 1/1 frequency division ratio	2.4 to 3.6		7	85		
	IDDHALT(4)		HALT mode • FmCF=0Hz (Oscillation stopped) • FsX'tal=32.768kHz crystal oscillation • Internal RC oscillation stopped • System clock set to 4MHz VMRC oscillation • 1/1 frequency division ratio	2.4 to 3.6		650	1460		
	IDDHALT(5)		HALT mode FmCF=0Hz (Oscillation stopped) FsX'tal=32.768kHz crystal oscillation Internal RC oscillation stopped System clock set to VMRC oscillation (500kHz) 1/1 frequency division ratio	2.4 to 3.6		68	280	μΑ	
	IDDHALT(6)		HALT mode • FmCF=0Hz (Oscillation stopped) • FsX'tal=32.768kHz crystal oscillation • System clock set to 32.768kHz side • Internal RC oscillation stopped. • VMRC oscillation stopped • 1/1 frequency division ratio • Normal XT amp mode	2.4 to 3.6		8	70		
	IDDHALT(7)		HALT mode • FmCF=0Hz (Oscillation stopped) • FsX'tal=32.768kHz crystal oscillation • System clock set to 32.768kHz side • Internal RC oscillation stopped. • VMRC oscillation stopped • 1/1 frequency division ratio • Low consumption XT amp mode	2.4 to 3.6		4	50		

Note 7-1: The consumption current value does not include current that flows into the output transistors and internal pull-up resistors.

Continued on next page.

D						ication	1		
Parameter	Symbol	Pin/Remarks	Conditions	V _{DD} [V]	min	typ	max	unit	
Current consumption in HOLD mode	IDDHOLD(1)	V _{DD} 1=V _{DD} 2 =V2	HOLD mode • CF1=V _{DD} or open (When using external clock)	2.4 to 3.6		0.05	30		
Current consumption in time-of-day clock HOLD mode	IDDHOLD(2)	V _{DD} 1=V _{DD} 2 =V2	Time-of-day clock HOLD mode • CF1=V _{DD} or open (When using external clock) • FsX'tal=32.768kHz crystal oscillation • 1/1 frequency division ratio • LCD display off • Normal XT amp mode	2.4 to 3.6		6.5	67		
	IDDHOLD(3)		Time-of-day clock HOLD mode • CF1=V _{DD} or open (When using external clock) • FsX'tal=32.768kHz crystal oscillation • 1/1 frequency division ratio • LCD display off • Low consumption XT amp mode	2.4 to 3.6		0.45	46	μΑ	
	IDDHOLD(4)		Time-of-day clock HOLD mode • CF1=V _{DD} or open (When using external clock) • FsX'tal=low-speed RC oscillation • 1/1 frequency division ratio • LCD display off	2.4 to 3.6		1.5	70		

Demonster	Querra ha a la Dia (Da erra a ritar				Specification				
Parameter	Symbol	Pin/Remarks	Conditions	V _{DD} [V]	min	typ	max	unit	
Onboard programming current	IDDFW(1)	V _{DD} 1	Excluding power dissipation in the microcontroller block	3.0 to 5.5		5	10	mA	
Programming	tFW(1)		 Erasing operation 	204-55		20	30	ms	
time	tFW(2)		 Programming operation 	3.0 to 5.5		45	60	μs	

UART (Full Duplex) Operating Conditions at $Ta = -40^{\circ}C$ to $+85^{\circ}C$, $V_{SS}1 = V_{SS}2 = 0V$

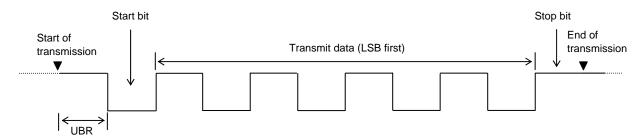
Parameter	Querra la cl	Pin/Remarks			Specification				
	Symbol		Conditions	V _{DD} [V]	min	typ	max	unit	
Transfer rate	UBR	UTX (P00),		244226	16/3		8192/3	tCYC	
		URX (P01)		2.4 to 3.6	10/3		0192/3		
Data length:	7/8/9 bits	(LSB first)							

Data length: Stop bits: Parity bits:

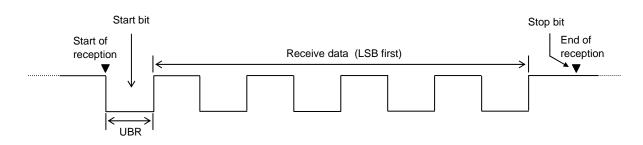
1 bit (2 bits in continuous data transmission)

None

Example of 8-bit Data Transmission Mode Processing (Transmit Data=55H)



Example of 8-bit Data Reception Mode Processing (Receive Data=55H)



Characteristics of a Sample Main System Clock Oscillator Circuit

Given below are the characteristics of a sample main system clock oscillator circuit, which are measured using a Our designated oscillation characteristics evaluation board and external components with circuit constant values with normal and stable oscillation confirmed by the resonator vendor.

Table 1 Characteristics of a Sample Main System Clock Oscinator Circuit with a Ceranic Resonator											
	Vendor		Circuit Constant				Operating Voltage	5			
	Name	Resonator Name	C1	C2	Rf1	Rd1	Range	typ	max	Remarks	
			[pF]	[pF]	[Ω]	[Ω]	[V]	[ms]	[ms]		
4.000411-	Murata	CSTCR4M00G53-R0	(15)	(15)	Open	1k	2.4 to 3.6	0.03	0.15	Internal	
4.00MHz	Murata	CSTLS4M00G53-B0	(15)	(15)	Open	1k	2.4 to 3.6	0.02	0.15	C1, C2	

Table 1 Characteristics of a Sample Main System Clock Oscillator Circuit with a Ceramic Resonator

The oscillation stabilization time is the period required for the resonator to stabilize in the following situations. (See Figure 4)

- After V_{DD} goes above the operating voltage lower limit until the oscillation is stabilized.
- After the instruction for starting the main clock oscillation circuit is executed until the oscillation is stabilized.
- After HOLD mode is released until the oscillation is stabilized.
- After HOLD mode is released and oscillation is started with CFSTOP (OCR register, bit0) set to 0 until the oscillation is stabilized.

Characteristics of a Sample Sub-system Clock Oscillator Circuit

Given below are the characteristics of a sample sub-system clock oscillator circuit, which are measured using a Our designated oscillation characteristics evaluation board and external components with circuit constant values with normal and stable oscillation confirmed by the resonator vendor. (Different evaluation boards are used for Tables 2 and 3.)

		a sampie sue eje													
Nominal Vendor Frequency Name	Vendor	Resonator Name	Circuit Constant				Operating Voltage	Oscillation Stabilization Time							
	Name		Resonator Name	Resonator Name	Resonator Name	Resonator Name	Resonator Name	Resonator Name	C3	C4	Rf2	Rd2	Range	typ	max
			[pF]	[pF]	[Ω]	[Ω]	[V]	[s]	[s]						
			9	9	Open	330k	2.4 to 3.6	1	3	CL=7.0pF Normal amp					
32.768KHz	Epson Toyocom	MC-306	3	3	Open	0	2.4 to 3.6	2	6	CL=7.0pF Low consumption amp					

Table 2 Characteristics of a Sample Sub-system Clock Oscillator Circuit with a Crystal Resonator 1

Table 3 Characteristics of a Sample Sub-system Clock Oscillator Circuit with a Crystal Resonator 2 (*5)

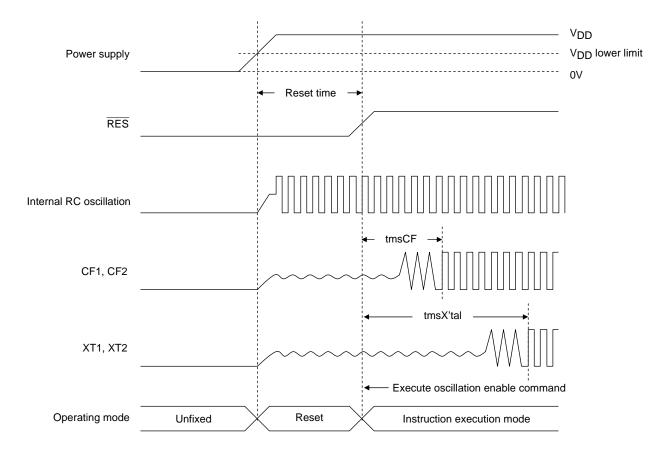
Nominal	V/	Resonator	Circuit Constant			Operating Voltage	Oscillation Stabilization Time		Demeriu	
Frequency Vendor Name	Name	C3 [pF]	C4 [pF]	Rf2 [Ω]	Rd2 [Ω]	Range [V]	typ [s]	max [s]	Remarks	
	Seiko Instruments (*2)	SSP-T7-F	22 22	Open	820k	2.4 to 3.6	1.8	3	CL=12.5pF (*3)	
32.768kHz		VT-200-F		22	Open	020K	2.4 10 3.0	1.0	5	Normal amp
(*1)		SSP-T7-FL	7	6	Open	0				CL=6.0pF (*4)
		VT-200-FL					2.4 to 3.6	6 0.9	3	Low consumption amp

(*1) Normal XT amplifier mode (*3) or low consumption amplifier mode (*4) should be selected for the sub-system clock oscillator circuit.

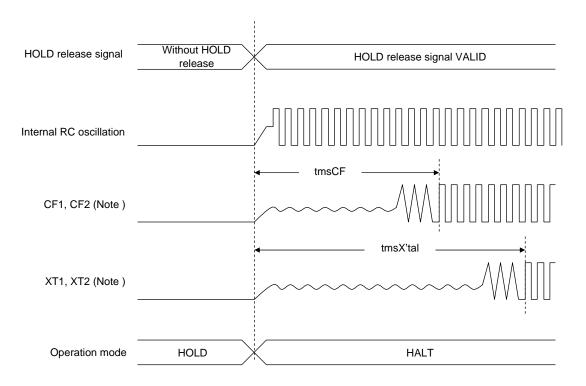
(*2) Contact Seiko Instruments, Inc., (<u>http://www.sii-crystal.com</u>) for further information about the use of the resonator.

(*3) When considering the use of normal XT amplifier mode, use an resonator that has a large load capacitance.

(*4) When considering the use of low consumption XT amplifier mode, use a resonator that has a small load capacitance. The applicable CL value of 6.0pF makes it possible to achieve a high time accuracy for the subclock oscillator as well as high-speed oscillation startup and low power dissipation. In addition to this value, 7.0pF and 9.0pF also fall within the applicable CL value range.

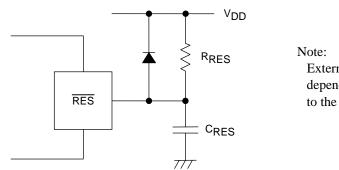


Reset Time and Oscillation Stabilization Time



HOLD Release Signal and Oscillation Stabilization Time Note: Oscillation is enabled before HOLD mode is entered.

Figure 4 Oscillation Stabilization Time



External circuits for reset may vary depending on the usage of POR. Please refer to the user's manual on reset function.



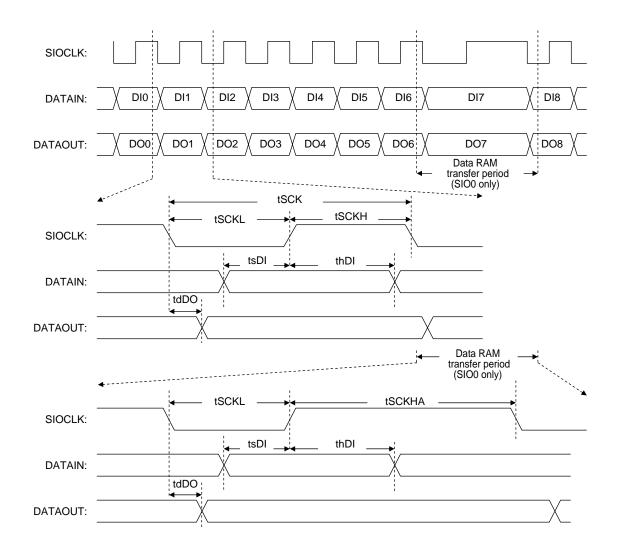


Figure 6 Serial Input/Output Waveform

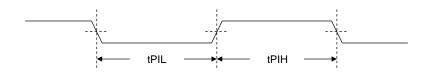
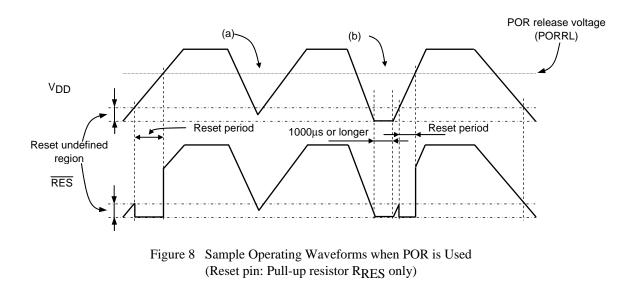


Figure 7 Pulse Input Timing Waveform



- The POR function generates a reset only when power is turned on starting at the VSS level.
- No stable reset will be generated if power is turned on again when the power level does not go down to the V_{SS} level as shown in (a).
- A reset is generated only when the power level goes down to the V_{SS} level as shown in (b) and power is turned on again after this condition continues for 1000 μ s or longer.

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